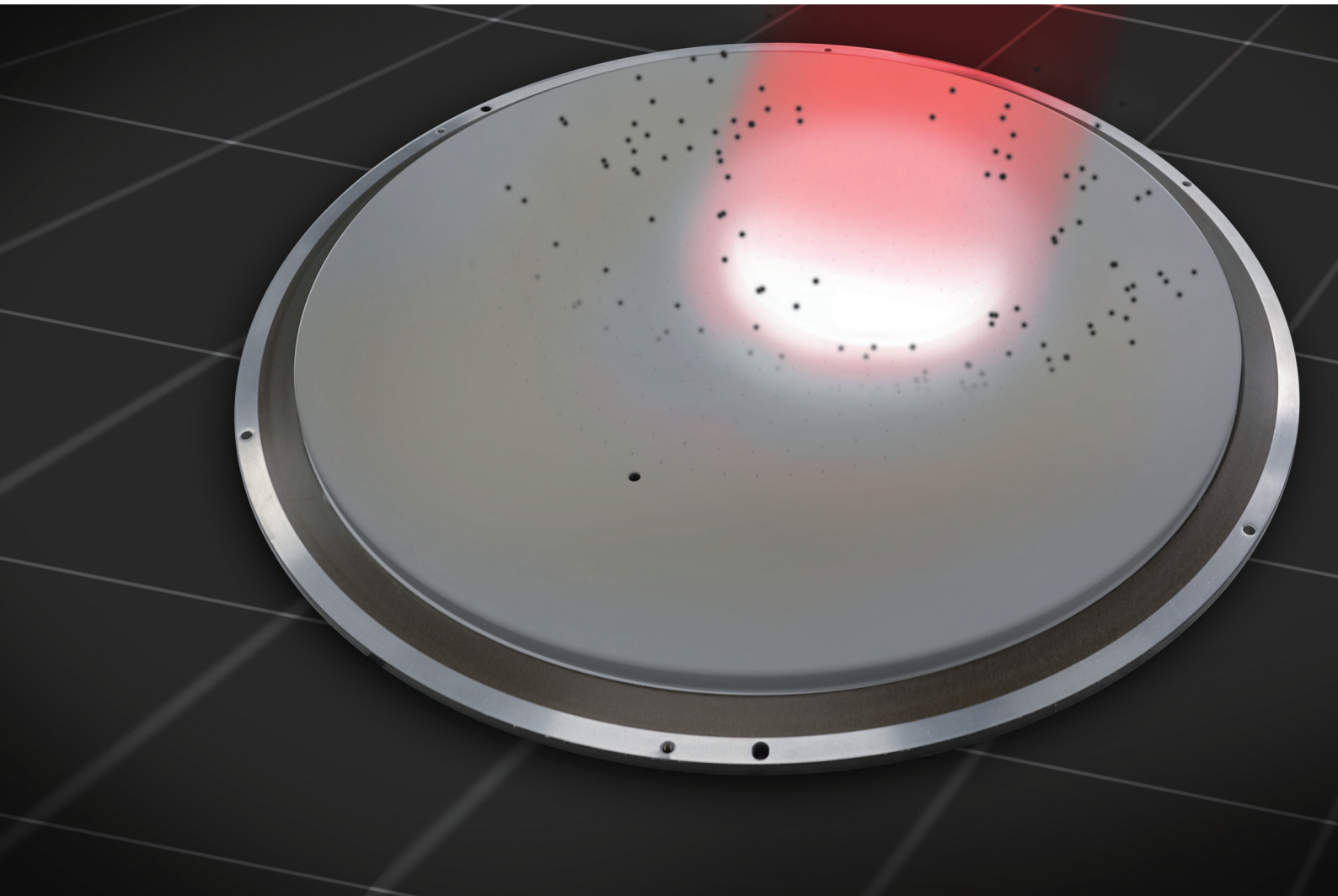


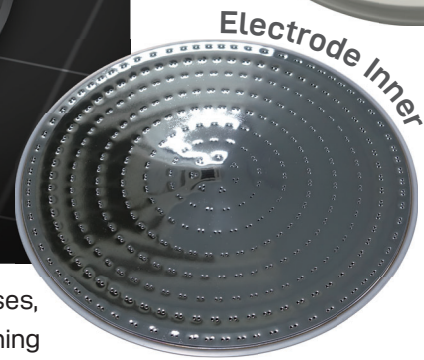
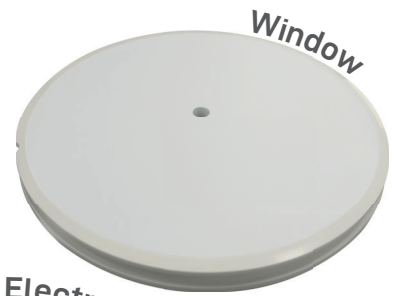
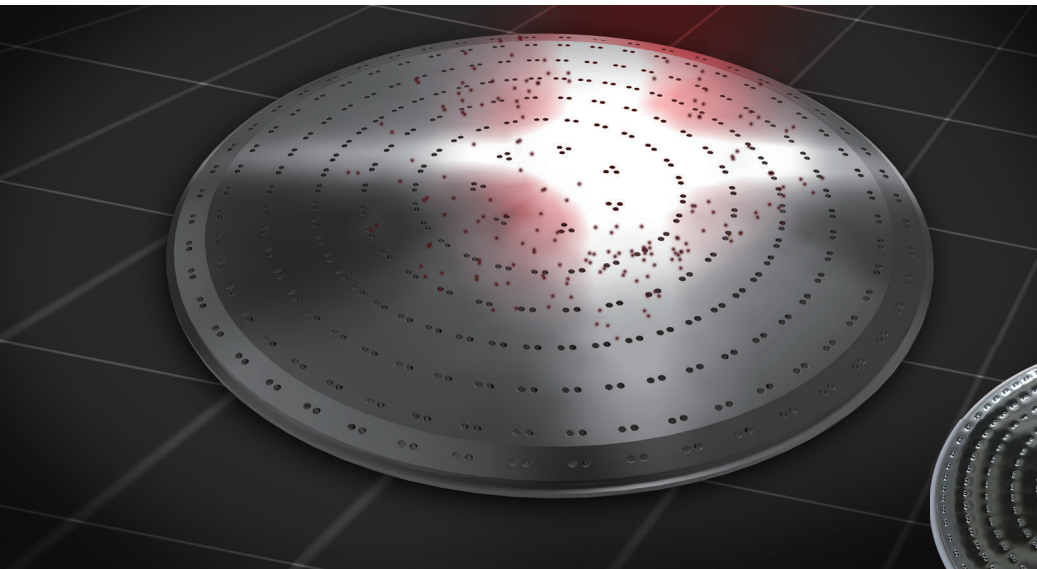
CINOS CLEANING TECHNOLOGY

Pulse Beam Clean

PBC™

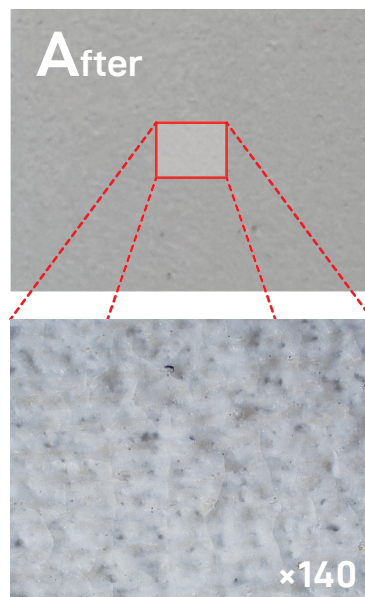
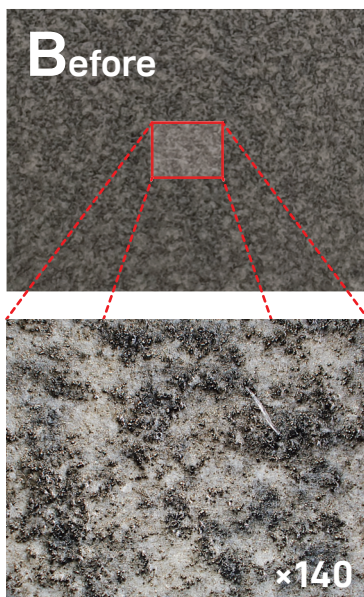
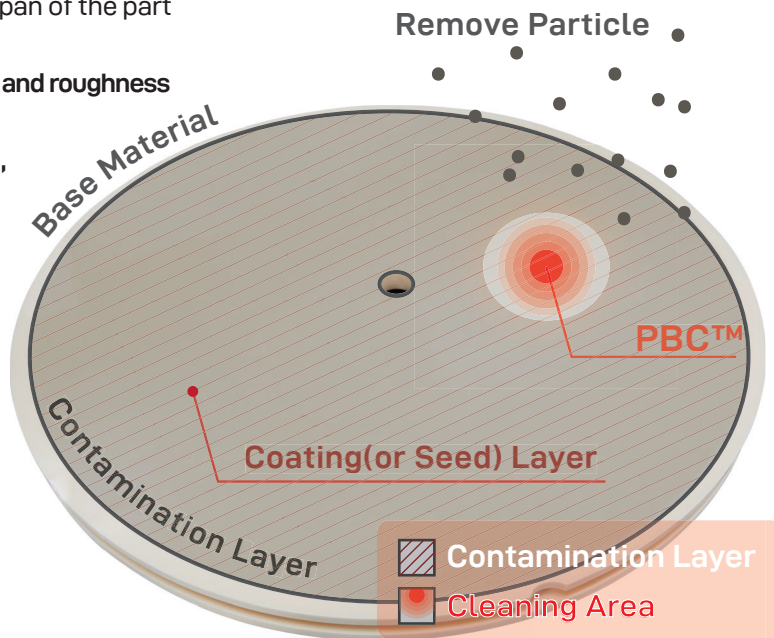
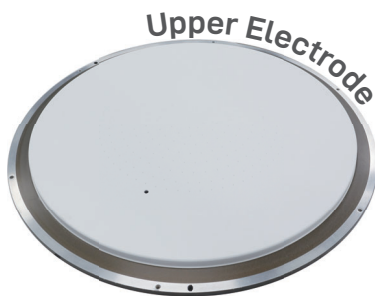


CINOS



As technology for cleaning products in general semiconductor processes, physical and chemical cleaning methods are applied, but pre-existing cleaning removes process by-products and at the same time causes problems such as etching and deformation of the substrate. It shortens the lifespan of the part and affects yield.

PBC™ is the cleaning method that does not affect the thickness and roughness of the substrate and coating area by selectively removing by-products generated during the process with pulse beam, thermal, and microplasma.



Thermal Expansion Effect

The difference in energy absorption coefficient with contamination → removed due to difference in coefficient of thermal expansion.



Decomposition and Phase Change of Contamination

It vaporizes by generating a high temperature of thousands degrees in the treatment area.



Pulse Oscillation

Decomposition by generating mechanical resonance in the treatment area.